504077222 11/02/2016

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1 Stylesheet Version v1.2 EPAS ID: PAT4123889

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
Kun-Ju Li	10/28/2016
Kuo-Chin Hung	10/28/2016
Min-Chuan Tsai	10/28/2016
Wei-Chuan Tsai	10/28/2016
Yi-Han Liao	10/28/2016
Chun-Tsen Lu	10/28/2016
Fu-Shou Tsai	10/28/2016
Li-Chieh Hsu	10/28/2016

RECEIVING PARTY DATA

Name:	UNITED MICROELECTRONICS CORP.
Street Address:	No.3, Li-Hsin Road 2, Science-Based Industrial Park
City:	Hsin-Chu City
State/Country:	TAIWAN

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	15340982

CORRESPONDENCE DATA

Fax Number: (703)997-4517

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

Phone: 3027291562

Email: Patent.admin.uspto.cr@naipo.com

Correspondent Name: WINSTON HSU Address Line 1: P.O.BOX 506

Address Line 4: MERRIFIELD, VIRGINIA 22116

ATTORNEY DOCKET NUMBER:	NAUP2845USA
NAME OF SUBMITTER:	KATE YEH
SIGNATURE:	/KATE YEH/
DATE SIGNED:	11/02/2016

PATENT REEL: 040191 FRAME: 0432

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Total Attachments: 16	
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Title of Invention:

CONDUCTIVE STRUCTURE, LAYOUT STRUCTURE INCLUDING CONDUCTIVE STRUCTURE, AND METHOD FOR MANUFACTURING CONDUCTIVE STRUCTURE

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(referred to as "ASSIGNEE"below) to acknowledged, andfor other good ar	o I of the sum of One nd valuable consider	e Dollar (\$ 1.00), t ation.	he receipt of whic	h is hereby
I hereby sell, assign and transfer to a the entire right, title and interest in a invention as above-identified applica invention by the above application of substitutes, or extensions thereof, ar	nd to any and all imp ition and, in and to, a r any continuations, (provements which all Letters Patent t continuation-in-pa	are disclosed in to be obtained for rt, divisions, rene	the said wals,
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I further covenant that ASSIGNEE wand documents relating to said inver known and accessible to I and will te related thereto and will promptly exe	ntion and said Letters estify as to the same	s Patent and legal in any interferenc	equivalents as me, litigation proce	nay be
representatives any and all papers, i maintain, issue and enforce said app equivalents thereof which may be ne IN WINTNESS WHEREOF, I have h	olication, said inventi ecessary or desirable	on and said Letter to carry out the p	rs Patent and said proposes thereof.	
Note: An application data sheet (PTC inventive entity, must accompany thi				

Page 1 of 16

F#NPO-P0002E-US1201 DSB0-105U023329

LEGAL NAME OF INVENTOR(ASSIGNOR)					
Inventor:	Kun-Ju Li		Date:	OCT 28 2016	
Signature:	Kun-Ju	Lì	•		

Page 2 of 16

NPO#NAU-P2845-USA:0 CUST#UMCD-2016-0454

Title of Invention:

CONDUCTIVE STRUCTURE, LAYOUT STRUCTURE INCLUDING CONDUCTIVE STRUCTURE, AND METHOD FOR MANUFACTURING CONDUCTIVE STRUCTURE

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l hereby acknowledge that any willfur under18 U.S.C. 1001 by fine or impri	I false statement made in this dec isonment of not more than five (5)	claration is punishable) years, or both.	
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(referred to as "ASSIGNEE"below) to acknowledged, andfor other good an	o I of the sum of One Dollar (\$ 1.0 d valuable consideration.	0), the receipt of which is he	ereby
I hereby sell, assign and transfer to A the entire right, title and interest in ar invention as above-identified applicat invention by the above application or substitutes, or extensions thereof, an	nd to any and all improvements w tion and, in and to, all Letters Pat any continuations, continuation-i	hich are disclosed in the ent to be obtained for said n-part, divisions, renewals	
I hereby covenant that no assignmen entered into which would conflict with	rt, sale, agreement or encumbran rthis assignment;	ce has been or will be made	or or
I further covenant that ASSIGNEE wi and documents relating to said inven known and accessible to I and will te related thereto and will promptly exec	tion and said Letters Patent and I stify as to the same in any interfe	egal equivalents as may be rence, litigation proceeding	cts
representatives any and all papers, in maintain, issue and enforce said app equivalents thereof which may be ne IN WINTNESS WHEREOF, I have he	lication, said invention and said L cessary or desirable to carry out t	etters Patent and said the proposes thereof.	of signing)
Note: An application data sheet (PTC inventive entity, must accompany this			

Page 3 of 16

NPO#NAU-P2845-USA:0 CUST#UMCD-2016-0454

LEGAL NAME OF INVENTOR(ASSIGNOR)					
Inventor:	Kuo-Chin Hung		Date:	OCT 2 8 2016	
Signature:	Kuo-Chin	Hung			

Page 4 of 16

Title of Invention:

CONDUCTIVE STRUCTURE, LAYOUT STRUCTURE INCLUDING CONDUCTIVE STRUCTURE, AND METHOD FOR MANUFACTURING CONDUCTIVE STRUCTURE

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I hereby sell, assign and transfer to a the entire right, title and interest in a invention as above-identified applica invention by the above application of substitutes, or extensions thereof, ar	nd to any and all improvements w tion and, in and to, all Letters Pat r any continuations, continuation-i	hich are disclosed ent to be obtained t n-part, divisions, re	in the for said enewals
I hereby covenant that no assignmer entered into which would conflict with	nt, sale, agreement or encumbran n this assignment;	ce has been or will	be made or
I further covenant that ASSIGNEE w and documents relating to said inven known and accessible to I and will te related thereto and will promptly exe	ition and said Letters Patent and I stify as to the same in any interfe	egal equivalents as rence. litigation pro	s may be
representatives any and all papers, in maintain, issue and enforce said app equivalents thereof which may be ne IN WINTNESS WHEREOF, I have he	lication, said invention and said L cessary or desirable to carry out t	etters Patent and s	said
Note: An application data sheet (PTC inventive entity, must accompany this	D/SB/14 or equivalent), including r s form. Use this form for <u>each add</u>	naming the entire itional inventor.	

Page 5 of 16

NPO#NAU-P2845-USA:0 CUST#UMCD-2016-0454

LEGAL NAME OF	INVENT	ror((ASSIGNOF	₹.
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Inventor: Min-Chuan Tsai Date: 007 2 8 2016

Signature: Min Chuan TSaT

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NPO#NAU-P2845-USA:0 CUST#UMCD-2016-0454

Title of Invention:

CONDUCTIVE STRUCTURE, LAYOUT STRUCTURE INCLUDING CONDUCTIVE STRUCTURE, AND METHOD FOR MANUFACTURING CONDUCTIVE STRUCTURE

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I hereby sell, assign and transfer to ASSIGNEE and the the entire right, title and interest in and to any and all im invention as above-identified application and, in and to, invention by the above application or any continuations, substitutes, or extensions thereof, and as to Letters Pat	provements which are all Letters Patent to be continuation-in-part, c ent any reissue or re-e	disclosed in the e obtained for said livisions, renewals, examination thereof	
I hereby covenant that no assignment, sale, agreement entered into which would conflict with this assignment;	or encumbrance has t	peen or will be mad	e or
I further covenant that ASSIGNEE will, upon its request and documents relating to said invention and said Lette known and accessible to I and will testify as to the same related thereto and will promptly execute and deliver to	rs Patent and legal equ e in any interference. Ii	uivalents as may be	à
representatives any and all papers, instruments or affida maintain, issue and enforce said application, said invent equivalents thereof which may be necessary or desirabl IN WINTNESS WHEREOF, I have hereunto set hand a	tion and said Letters P le to carry out the prop	atent and said oses thereof.	of signing)
Note: An application data sheet (PTO/SB/14 or equivale nventive entity, must accompany this form. Use this form	nt), including naming t m for <u>each additional i</u>	he entire	

Page 7 of 16

NPO#NAU-P2845-USA:0 CUST#UMCD-2016-0454

LEGAL NAME OF INVENTOR(ASSIGNOR)

Inventor: Wei-Chuan Tsai Date:

OCT 28 2016

Signature:

Wei-Chuan Tsai

Page

F#NPO-P0002E-US1201

Title of Invention:

CONDUCTIVE STRUCTURE, LAYOUT STRUCTURE INCLUDING CONDUCTIVE STRUCTURE, AND METHOD FOR MANUFACTURING CONDUCTIVE STRUCTURE

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representatives any and all papers, i maintain, issue and enforce said app equivalents thereof which may be ne N WINTNESS WHEREOF, I have h	olication, said invention and said lecessary or desirable to carry out	_etters Patent and said	s i gning)
Note: An application data sheet (PTonventive entity, must accompany thi			

Page 9 of 16

NPO#NAU-P2845-USA:0 CUST#UMCD-2016-0454

LEGAL NAME OF INVENTOR(ASSIGNOR)

Inventor: Yi-Han Liao Date: 0CT 2 8 2016

Signature: Yi - Han Liao

Page 10 of 16

NPO#NAU-P2845-USA:0 CUST#UMCD-2016-0454

Title of Invention:

CONDUCTIVE STRUCTURE, LAYOUT STRUCTURE INCLUDING CONDUCTIVE STRUCTURE, AND METHOD FOR MANUFACTURING CONDUCTIVE STRUCTURE

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Page 11 of 16

NPO#NAU-P2845-USA:0 CUST#UMCD-2016-0454

LEGAL NAME OF INVENTOR(ASSIGNOR)					
Inventor:	Chun-Tsen Lu	Date:	OCT 2 8 2016		
Signature:	Chym-Teen	ln			

Page 12 of 16

NPO#NAU-P2845-USA:0 CUST#UMCD-2016-0454

Title of Invention:

CONDUCTIVE STRUCTURE, LAYOUT STRUCTURE INCLUDING CONDUCTIVE STRUCTURE, AND METHOD FOR MANUFACTURING CONDUCTIVE STRUCTURE

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Page 13 of 16

LEGAL NAME OF INVENTOR(ASSIGNOR)

Inventor:

Fu-Shou Tsai

Date:

OCT 2 8 2016

Page 14 of 16

Title of Invention:

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Page 15 of 16

NPO#NAU-P2845-USA:0 CUST#UMCD-2016-0454

LEGAL NAI	ME OF INVENTOR(ASSIGN	IOR)			
Inventor:	Li-Chieh Hsu		Date:	OCT 2 8 2016	
Signature:	Ci-Chiela	Han			

Page 16 of 16

NPO#NAU-P2845-USA:0 CUST#UMCD-2016-0454

RECORDED: 11/02/2016

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